

IGBT Power Module

1200V / 400A

Preliminary

Features

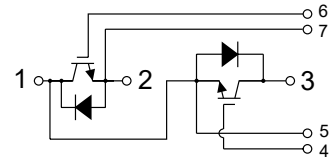
- ◆ 62mm Fast Switching / Trench Field Stop IGBT Technology
- ◆ Low Switching Losses
- ◆ Super Fast Diodes
- ◆ High Short Circuit Capability

Applications

- ◆ Welder / Power Supply
- ◆ UPS / Inverter
- ◆ Industrial Motor Drive



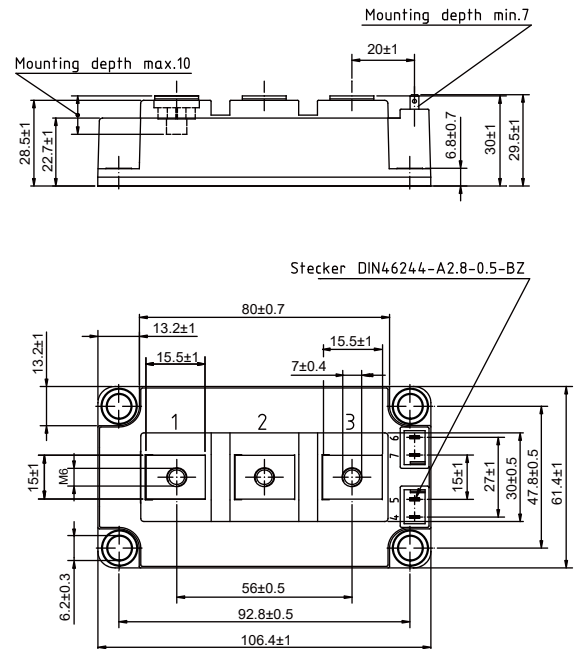
Circuit Diagram Headline



Maximum Ratings (T_C = 25°C)

Item	Symbol	Rated Value	Unit
Collector-Emitter Voltage	T _{VJ} = 25°C V _{CES}	1200	V
Gate-Emitter Peak Voltage	V _{GES}	±20	V
Continuous DC Collector Current	T _H = 85°C T _{VJ max.} = 175°C I _{C, nom.}	400	A
Repetitive Peak Collector Current	t _p = 1ms I _{CRM}	800	A
Total Power Dissipation	P _{tot}	2100	W
Isolation Voltage	RMS, f=50Hz, t=1min V _{iso}	3000	V
Max. Junction Temperature	TV _{J max.}	175	°C
Temperature Under Switching Conditions	TV _{J op}	-40 ~ +150	°C
Storage Temperature	T _{stg}	-40 ~ +125	°C
Mounting Torque	Module Base to Heatsink (M6)	3~6	N.m
	Busbar to Terminal (M6)	2.5~5	

Package Outlines



Dimensions in mm (1 mm = 0.0394")

■ Electrical Characteristics

Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Collector-emitter saturation voltage	$V_{CE\ sat}$	$I_C = 400A, V_{GE} = 15V$ $T_{vj} = 25^\circ C$ $I_C = 400A, V_{GE} = 15V$ $T_{vj} = 125^\circ C$		1.80 2.10	2.10	V
Gate threshold voltage	$V_{GE\ th}$	$I_C = 5.3mA, V_{CE} = V_{GE}, T_{vj} = 25^\circ C$	4.9	5.4	5.9	V
Gate charge	Q_G	$I_C = 400A, V_{CE} = 600V, V_{GE} = 15V$		857		nC
Internal gate resistor	R_{Gint}	$T_{vj} = 25^\circ C$		1.0		Ω
Input capacitance	C_{ies}	$f = 100KHz, T_{vj} = 25^\circ C, V_{CE} = 25V, V_{GE} = 0V$		49		nF
Output capacitance	C_{oes}	$f = 100KHz, T_{vj} = 25^\circ C, V_{CE} = 25V, V_{GE} = 0V$		1.5		nF
Reverse transfer capacitance	C_{res}	$f = 100KHz, T_{vj} = 25^\circ C, V_{CE} = 25V, V_{GE} = 0V$		0.232		nF
Collector-emitter cut-off current	I_{CES}	$V_{CE} = 1200V, V_{GE} = 0V, T_{vj} = 25^\circ C$			5	mA
Gate-emitter leakage current	I_{GES}	$V_{CE} = 0V, V_{GE} = 20V, T_{vj} = 25^\circ C$			400	nA
Turn-on delay time, inductive load	$t_{d\ on}$	$I_C = 400A, V_{CE} = 600V$ $T_{vj} = 25^\circ C$		286		ns
		$V_{GE} = \pm 15V$ $T_{vj} = 125^\circ C$		295		
		$R_{G(on)} = 1.8\Omega, R_{G(off)} = 1.8\Omega$ $T_{vj} = 150^\circ C$		295		
Rise time, inductive load	t_r	$I_C = 400A, V_{CE} = 600V$ $T_{vj} = 25^\circ C$		63		ns
		$V_{GE} = \pm 15V$ $T_{vj} = 125^\circ C$		59		
		$R_{G(on)} = 1.8\Omega, R_{G(off)} = 1.8\Omega$ $T_{vj} = 150^\circ C$		64		
Turn-off delay time, inductive load	$t_{d\ off}$	$I_C = 400A, V_{CE} = 600V$ $T_{vj} = 25^\circ C$		255		ns
		$V_{GE} = \pm 15V$ $T_{vj} = 125^\circ C$		290		
		$R_{G(on)} = 1.8\Omega, R_{G(off)} = 1.8\Omega$ $T_{vj} = 150^\circ C$		294		
Fall time, inductive load	t_f	$I_C = 400A, V_{CE} = 600V$ $T_{vj} = 25^\circ C$		80		ns
		$V_{GE} = \pm 15V$ $T_{vj} = 125^\circ C$		107		
		$R_{G(on)} = 1.8\Omega, R_{G(off)} = 1.8\Omega$ $T_{vj} = 150^\circ C$		132		
Turn-on energy loss per pulse	E_{on}	$I_C = 400A, V_{CE} = 600V$ $T_{vj} = 25^\circ C$		10		mJ
		$V_{GE} = \pm 15V$ $T_{vj} = 125^\circ C$		19		
		$R_{G(on)} = 1.8\Omega, R_{G(off)} = 1.8\Omega$ $T_{vj} = 150^\circ C$		20		
Turn-off energy loss per pulse	E_{off}	$I_C = 400A, V_{CE} = 600V$ $T_{vj} = 25^\circ C$		33		mJ
		$V_{GE} = \pm 15V$ $T_{vj} = 125^\circ C$		40		
		$R_{G(on)} = 1.8\Omega, R_{G(off)} = 1.8\Omega$ $T_{vj} = 150^\circ C$		39		
SC data	I_{SC}	$V_{GE} \leq 15V, V_{CC} = 800V$ $V_{CEmax} = V_{CES} - L_{sCE} \cdot di/dt$ $t_p \leq 10\mu s, T_{vj} = 150^\circ C$		1800		A
Thermal resistance, junction to case	R_{thJC}	per IGBT			0.07	$^\circ C/W$

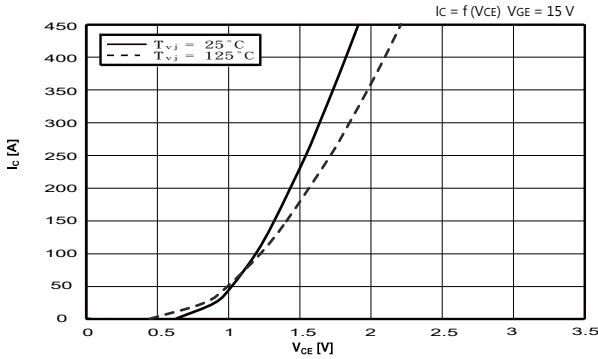
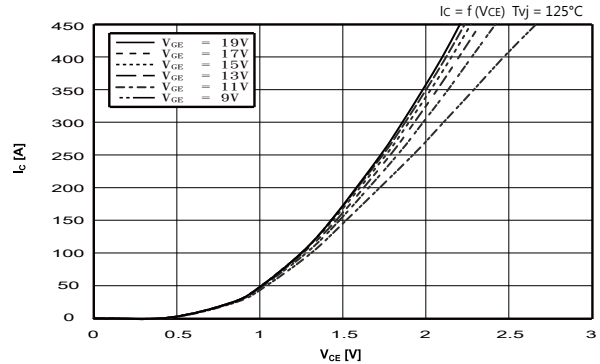
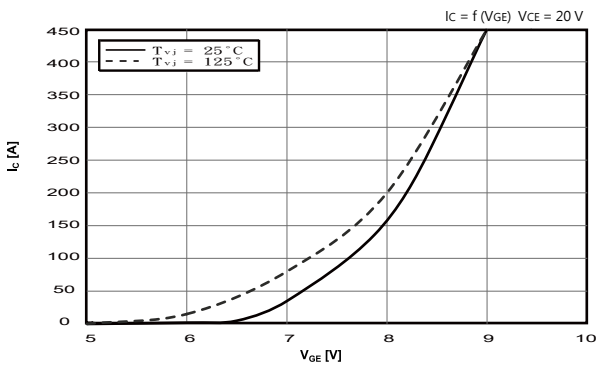
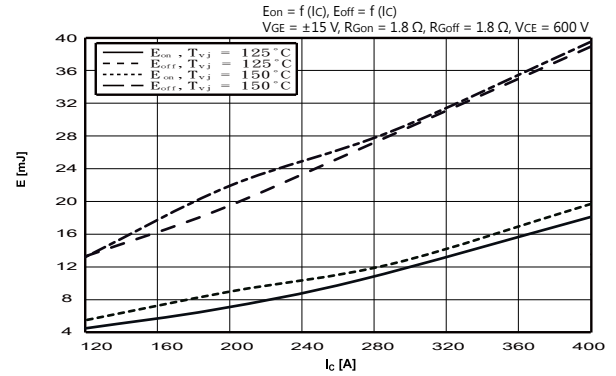
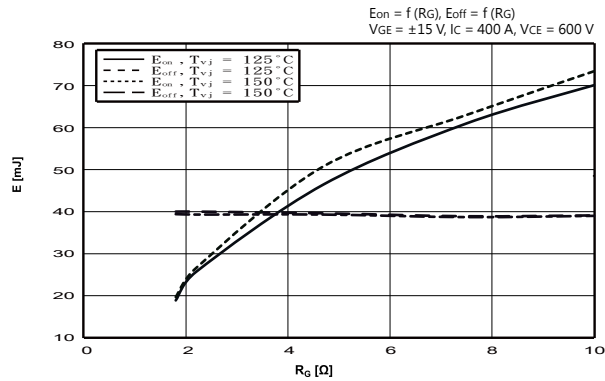
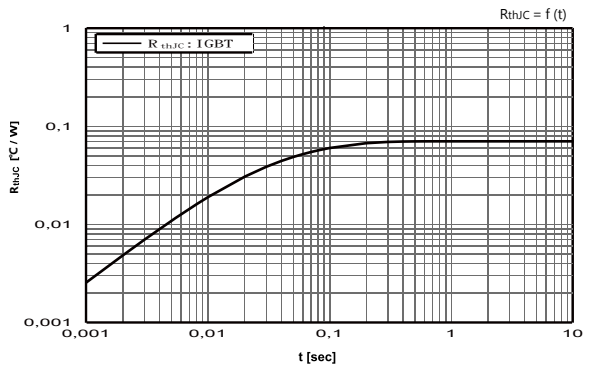
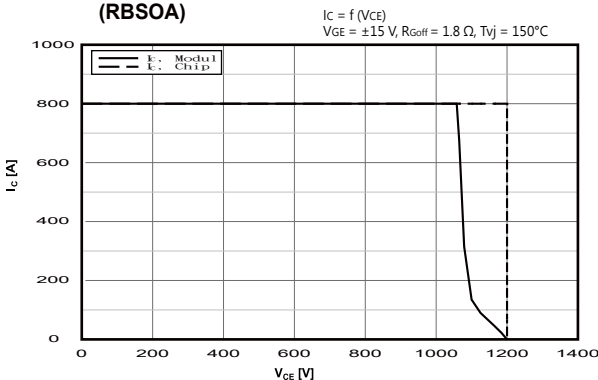
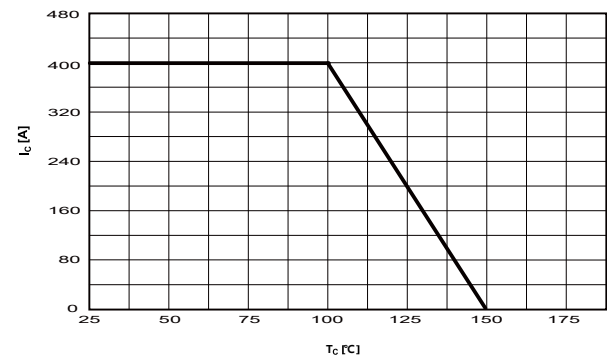
■ Diode Ratings & Characteristics

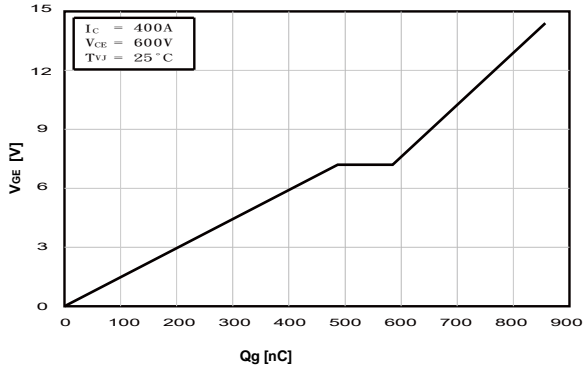
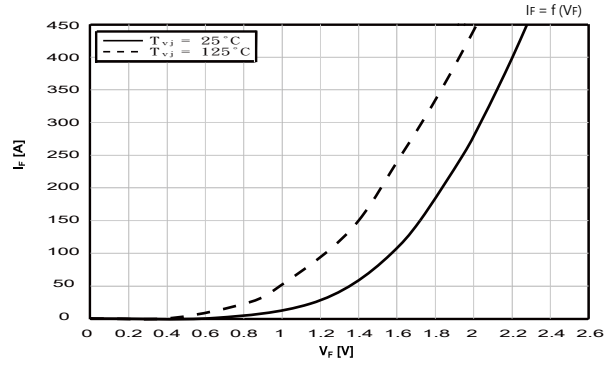
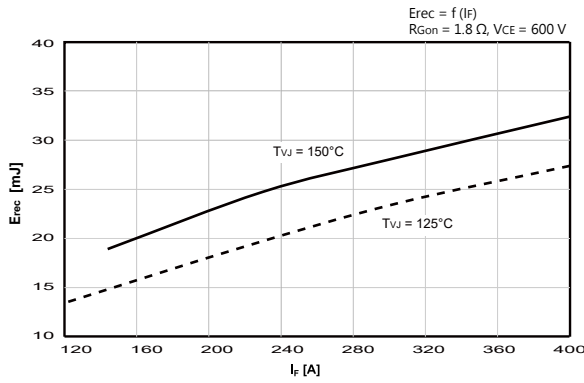
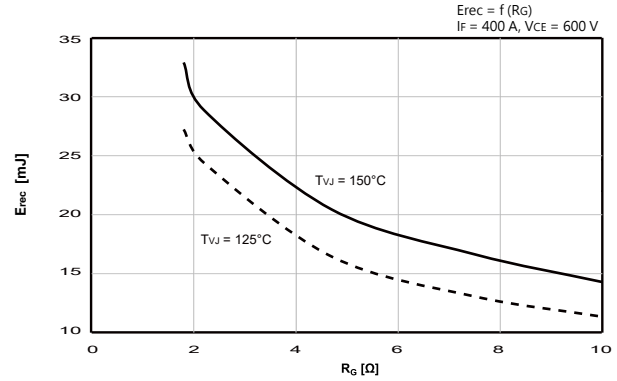
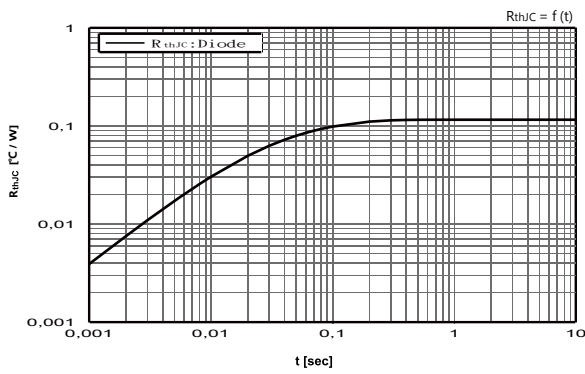
Symbol	Test Conditions	Value	Unit
V_{RRM}	$T_{vj} = 25^{\circ}\text{C}$	1200	V
I_F		400	A
I_{FRM}	$t_p = 1\text{ms}$	800	A
I^2t	$V_R = 0\text{V}, t_p = 10\text{ms}, T_{vj} = 125^{\circ}\text{C}$	34000	A ² s
	$V_R = 0\text{V}, t_p = 10\text{ms}, T_{vj} = 150^{\circ}\text{C}$	32000	

Symbol	Test Conditions	Min.	Typ.	Max.	Unit
V_F	$I_F = 400\text{A}, V_{GE} = 0\text{V}$ $T_{vj} = 25^{\circ}\text{C}$		2.2	2.35	V
	$I_F = 400\text{A}, V_{GE} = 0\text{V}$ $T_{vj} = 125^{\circ}\text{C}$		1.9		
I_{RRM}	$I_F = 400\text{A}, -di_F/dt = 4900\text{A}/\mu\text{s}$ $T_{vj} = 25^{\circ}\text{C}$		240		A
	$V_R = 600\text{V}$ $T_{vj} = 125^{\circ}\text{C}$		384		
	$V_{GE} = \pm 15\text{V}$ $T_{vj} = 150^{\circ}\text{C}$		424		
Qrr	$I_F = 400\text{A}, -di_F/dt = 4900\text{A}/\mu\text{s}$ $T_{vj} = 25^{\circ}\text{C}$		22540		nC
	$V_R = 600\text{V}$ $T_{vj} = 125^{\circ}\text{C}$		54140		
	$V_{GE} = \pm 15\text{V}$ $T_{vj} = 150^{\circ}\text{C}$		65370		
Erec	$I_F = 400\text{A}, -di_F/dt = 4900\text{A}/\mu\text{s}$ $T_{vj} = 25^{\circ}\text{C}$		12140		uJ
	$V_R = 600\text{V}$ $T_{vj} = 125^{\circ}\text{C}$		27240		
	$V_{GE} = \pm 15\text{V}$ $T_{vj} = 150^{\circ}\text{C}$		32910		
Trr	$I_F = 400\text{A}, -di_F/dt = 4900\text{A}/\mu\text{s}, V_R = 600\text{V}, V_{GE} = \pm 15\text{V}, T_{vj} = 25^{\circ}\text{C}$		221		ns
R_{thJC}	per diode			0.12	$^{\circ}\text{C}/\text{W}$
$T_{vj\text{ op}}$		-40		150	$^{\circ}\text{C}$

■ Module Ratings & Characteristics

Characteristics	Symbol	Test Conditions	Value	Unit
Material of module baseplate			Cu	
Internal isolation		basic insulation (class 1, IEC 61140)	Al_2O_3	
Creepage distance		terminal to heatsink	29	mm
		terminal to terminal	23	
Clearance		terminal to heatsink	23	mm
		terminal to terminal	11	
Comperative tracking index	CTI		>400	

Typical Characteristics
Preliminary Data
Fig.1 Output characteristic IGBT, Inverter (typical)

Fig.2 Output characteristic IGBT, Inverter (typical)

Fig.3 Transfer characteristic IGBT, Inverter (typical)

Fig.4 Switching losses IGBT, Inverter (typical)

Fig.5 Switching losses IGBT, Inverter (typical)

Fig.6 Transient thermal impedance IGBT, Inverter

Fig.7 Reverse bias safe operating area IGBT, Inverter (RBSOA)

Fig.8 Output characteristic IGBT, Inverter (typical)


Typical Characteristics
Preliminary Data
Fig.9 Gate Charge Characteristics(typical)

Fig.10 Forward characteristic of Diode, Inverter (typical)

Fig.11 Switching losses Diode, Inverter (typical)

Fig.12 Switching losses Diode, Inverter (typical)

Fig.13 Transient thermal impedance Diode, Inverter


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